2.5V / 3.3V, 6.125Gb/s 1:10 Differential Clock/Data Driver with CML Output

Description

The NB7L111M is a low skew 1-to-10 differential clock/data driver, designed with clock/data distribution in mind. It accepts two clock/data sources into multiplexer input and reproduces ten identical CML differential outputs. This device is ideal for clock/data distribution across the backplane or a board, and redundant clock switchover applications.

The input signals can be either differential or single–ended (if the external reference voltage is provided). Differential inputs incorporate internal 50 Ω termination resistors and accept Negative ECL (NECL), Positive ECL (PECL), LVCMOS, LVTTL, CML, or LVDS (using appropriate power supplies). The differential 16 mA CML output provides matching internal 50 Ω termination, and 400 mV output swing when externally terminated 50 Ω to V_{CC} .

The NB7L111M operates from a 2.5 V $\pm 5\%$ supply or a 3.3 V $\pm 5\%$ supply and is guaranteed over the full industrial temperature range of -40° C to $+85^{\circ}$ C. This device is packaged in a low profile 8x8 mm, QFN-52 package with 0.5 mm pitch (see package dimension on the back of the da as lee).

Application in ctes in ocell, and support documentation are available at www.onsemi.com.

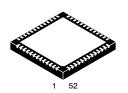
Features

- Maximum Input Clock Frequency > 5.5 GHz Typical
- Maximum Input Data Rate > 6.125 Gb/s Typical
- < 0.5 ps Maximum Clock RMS Jitter
- < 15 ps Maximum Data Dependent Jitter at 3.125 Gb/s
- 50 ps Typical Rise and Fall Times
- 240 ps Typical Propagation Delay
- 2 ps Typical Duty Cycle Skew
- 10 ps Typical Within Device Skew
- 15 ps Typical Device-to-Device Skew
- Operating Range: $V_{CC} = 2.5 \text{ V} \pm 5 \text{ and } 3.3 \text{ V} \pm 5$
- 400 mV Differential CML Output Swing
- 50 Ω Internal Input and Output Termination Resistors
- Pb-Free Packages are Available*



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QFN-52 MN SUFFIX CASE 485M

MARKING DIAGRAM*



*For additional marking information, refer to

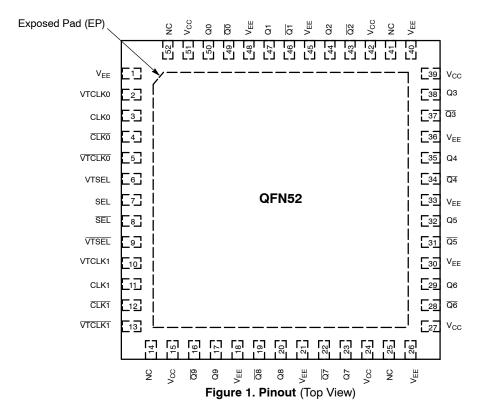
= Pb-Free Package

Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



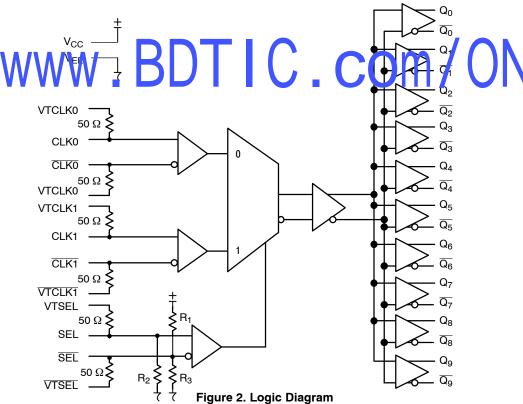


Table 1. FUNCTION TABLE

| SEL | SEL | CLK0/CLK0 | CLK1/CLK1 |
|------|------|-----------|-----------|
| LOW | HIGH | ON | OFF |
| HIGH | LOW | OFF | ON |

Table 2. PIN DESCRIPTION

| Pin | Name | I/O | Description |
|---|-----------------|--|---|
| 15, 24, 27, 39, 42, 51 | V _{CC} | - | Positive supply voltage. All $V_{\rm CC}$ pins must be externally connected to power supply to guarantee proper operation. |
| 1, 18, 21, 26, 30, 33, 36, 40, 45, 48 | V _{EE} | - | Negative supply voltage. All V_{EE} pins must be externally connected to power supply to guarantee proper operation. |
| 2 | VTCLK0 | - | Internal 50 Ω termination pin for CLK0. (Note 2) |
| 3 | CLK0 | LVPECL, CML, LVCMOS, LVTTL, LVDS Input | Non-inverted differential clock/data input 0 (Note 2). |
| 4 | CLK0 | LVPECL, CML, LVCMOS, LVTTL, LVDS Input | Inverted differential clock/data input 0 (Note 2). |
| 5 | VTCLK0 | - | Internal 50 Ω termination pin for $\overline{\text{CLK0}}$. (Note 2) |
| 6 | VTSEL | | Internal 50 Ω termination pin for SEL. (Note 2) |
| 7 | SEL | LVPECL, CML, LVCMOS, LVTTL, LVDS Input | Non-inverted differential clock/data select input. Internal 75 k Ω to V_{EE} . |
| 8 | SEL | LVPECL, CML, LVCMOS, LVTTL, LVDS Input | Inverted differential clock/data select input. Internal 56 K Ω to V _{CC} and 56 k Ω to V _{EE} bias this pin to (V _{CC} -V _{EE})/2. |
| 9 | VTSEL | LVPECL, CML, LVCMOS, LVTTL, LVDS Input | Internal 50 Ω termination pin for SEL. (Note 2) |
| 10 | VTCLK1 | - | Internal 50 Ω termination pin for CLK1. (Note 2) |
| 11 | CLK1 | LVPECL, CML, CMCS, LVETL, LV DS npu | Non-inverted differential clock/data input 1 (Note 2). |
| 12 V V | d LK1 | L /F ECL, CM _, LvCMGS, LVT TL, LVDS Input | nve ted /lifferential clock, tata in bu 1 (Note 2). |
| 13 | VTCLK1 | - | Internal 50 Ω termination pin for $\overline{\text{CLK1}}$. (Note 2) |
| 14, 25, 41, 52 | NC | - | |
| 17, 20, 23, 29, 32, 35, 38, 44, 47, 50 | Q[0-9] | CML Outputs | Non–inverted CML outputs [0–9] with internal 50 Ω source termination resistor (Note 1). |
| 16, 19, 22, 28, 31, 34, 37, 43, 46, 49 | Q[0-9] | CML Outputs | Inverted CML outputs [0–9] with internal 50 Ω source termination resistor (Note 1). |
| EP | I | - | Exposed Pad (EP). The thermally exposed pad on package bottom (see case drawing) must be attached to a heat-sinking conduit on the printed circuit board. |

CML output requires 50 Ω receiver termination resistor to V_{CC} for proper operation.
 In the differential configuration when the input termination pin (VTCLK, VTCLK) are connected to a common termination voltage or left open, and if no signal is applied on CLK and CLK then the device will be susceptible to self–oscillation.

Table 3. ATTRIBUTES

| Characteris | Value | | | | |
|--|-----------------------------------|--------------------|-------------|--|--|
| Input Default State Resistors | R1, R3 R2 | _ | | | |
| ESD Protection | Human Body Model Machine Model | > 1400 V > 80 V | | | |
| Moisture Sensitivity (Note 3) | | Pb Pkg | Pb-Free Pkg | | |
| | QFN-52 | Level 2 | Level 1 | | |
| Flammability Rating | UL 94 V-0 | @ 0.125 in | | | |
| Transistor Count | 30 | 39 | | | |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | | | | | |

^{3.} For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS (Note 4)

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|-------------------|---|--|-----------------------------|---|----------|
| V _{CC} | Positive Power Supply | V _{EE} = 0 V | | 3.6 | V |
| VI | Input Voltage | V _{EE} = 0 V | $V_{EE} \le V_I \le V_{CC}$ | 3.6 | V |
| V _{INPP} | Differential Input Voltage CLK - CLK | $\begin{array}{c} V_{CC} - V_{EE} \geq 2.8 \ V \\ V_{CC} - V_{EE} < 2.8 \ V \end{array}$ | | 2.8 V _{CC} – V _{EE} | V |
| l _{in} | Input Current Through R _T (50 Ω Resistor) | Continuous Surge | | 25 50 | mA mA |
| I _{out} | Output Current | Continuous Surge | | 25 50 | mA mA |
| T _A | Operating Temperature Range | QFN i2 | 00 M | -40 tc 85 | °C |
| T _{stg} | Stylage Tenirer itulir Range | 1 . | | -65 to -100 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) (Note 5) | 0 lfpm 500 lfpm | QFN52 | 25 19.6 | °C/W |
| $\theta_{\sf JC}$ | Thermal Resistance (Junction-to-Case) | 1S2P (Note 8) | QFN52 | 21 | °C/W |
| T _{sol} | Wave Solder Pb Pb-Free | | | 265 265 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

4. Maximum Ratings are those values beyond which device damage may occur.

5. JEDEC standard multilayer board – 1S2P (1 signal, 2 power).

Table 5. DC CHARACTERISTICS $V_{CC} = 2.375 \text{ V} 2.625 \text{ V}$ and 3.135 V to 3.465 V, $V_{EE} = 0 \text{ V}$, $T_A = -40 ^{\circ}\text{C}$ to $+85 ^{\circ}\text{C}$ (Notes 6 and 7)

| Symbol | Characteristic | Min | Тур | Max | Unit |
|---------------------------|---|--|--|--|------|
| I _{CC} | Power Supply Current (Inputs and Outputs Open) $ V_{CC} = 2.375 \ V \ to \ 2.625 \ V \\ V_{CC} = 3.135 \ V \ to \ 3.465 \ V $ | 255 270 | 290 305 | 325 340 | mA |
| V _{OH} | Output HIGH Voltage (Notes 6 and 7) | V _{CC} - 40 | V _{CC} – 20 | V _{CC} | mV |
| V _{OL} | Output LOW Voltage (Notes 6 and 7) $V_{CC} = 2.375 \text{ V to } 2.625 \text{ V} $ $V_{CC} = 3.135 \text{ V to } 3.465 \text{ V}$ | V _{CC} - 440 V _{CC} - 490 | V _{CC} - 350 V _{CC} - 400 | V _{CC} – 290 V _{CC} – 340 | mV |
| DIFFERE | NTIAL INPUT DRIVEN SINGLE-ENDED (See Figures 13 and 15) | | | | |
| V_{th} | Input Threshold Reference Voltage Range (Note 8) | 1125 | | V _{CC} – 75 | mV |
| V _{IH} | Single-ended Input HIGH Voltage (Note 7) | V _{th} + 75 | | V _{CC} | mV |
| V _{IL} | Single-ended Input LOW Voltage (Note 7) | | | V _{CC} – 150 | mV |
| DIFFERE | NTIAL INPUTS DRIVEN DIFFERENTIALLY (See Figures 14 and 16) | • | | • | |
| V_{IHD} | Differential Input HIGH Voltage | 1200 | | V _{CC} | mV |
| V_{ILD} | Differential Input LOW Voltage | | | V _{CC} – 75 | mV |
| V _{CMR} | Input Common Mode Range (Differential Configuration) (Note 9) | 1163 | | V _{CC} – 37 | mV |
| V _{ID} | Differential Input Voltage (V _{IHD} – V _{ILD}) | 75 | | 2500 | mV |
| I _{IH} | Input HIGH Current CLK[0-1]/CLK[0-1] (Termination Pins Open) SEL/SEL | -100 -150 | 5 | 100 150 | μΑ |
| I _{IL} | Input LOW Current CLK[0-1]/CLK[0-1] (Termination Pins Open) SEL/SEL | -100 -150 | 5 | 100 150 | μΑ |
| R _{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | Ω |
| R _{TOUT} | Internal Output Termination Resistor | 45 | 50 | 55 | Ω |
| R _{Temp} Coef | Internal IO Termination Resist ** Temperature Coefficient | CON | -3.75 | | mΩ/C |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 6. CML outputs require 50 Ω receiver termination resistors to V_{CC} for proper operation.
- 7. Input and output parameters vary 1:1 with V_{CC}.
- 8. V_{th} is applied to the complementary input when operating in single-ended mode.
- 9. $V_{CMR}(MIN)$ varies 1:1 with V_{EE} , $V_{CMR}(MAX)$ varies 1:1 with V_{CC} .

Table 6. AC CHARACTERISTICS $V_{CC} = 2.375 \text{ V}$ to 2.625 V and 3.135 V to 3.465 V, $V_{EE} = 0 \text{ V}$; (Note 10)

| | | -40°C | | 25°C | | | 85°C | | | | |
|--|--|--------------------------|-----------------------------|------------------------------|--------------------------|-----------------------------|------------------------------|--------------------------|-----------------------------|------------------------------|------|
| Symbol | Characteristic | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| V _{OUTPP} | Output Voltage Amplitude (@ $V_{inppmin}$) (See Figures 3, 4, 5, and 6) $V_{CC} = 2.375 \text{ V to } 2.625 \text{ V}$ $f_{in} \leq 3 \text{ GHz}$ $f_{in} \leq 5.5 \text{ GHz}$ $V_{CC} = 3.135 \text{ V to } 3.465 \text{ V}$ $f_{in} \leq 3 \text{ GHz}$ $f_{in} \leq 5.5 \text{ GHz}$ | 240 115 250 130 | 330 220 350 250 | | 240 115 250 130 | 330 220 350 250 | | 240 115 250 130 | 330 220 350 250 | | mV |
| f _{DATA} | Maximum Operating Data Rate | 5 | 6 | | 5 | 6 | | 5 | 6 | | Gb/s |
| t _{PLH} , t _{PHL} | Differential Input-to-Output Propagation Delay @ 1 GHz (See Figures 7 and 11) CLK-Q SEL-Q | 200 290 | 240 340 | 280 390 | 200 290 | 240 340 | 280 390 | 200 290 | 240 340 | 280 390 | ps |
| t _{SKEW} | Duty Cycle Skew (Note 11) Within Device Skew Device-to-Device Skew (Note 15) | | 2 10 15 | 15 20 80 | | 2 10 15 | 15 20 80 | | 2 10 15 | 15 20 80 | ps |
| UITTER | RMS Random Clock Jitter (Note 13) $f_{in} = 3 \text{ GHz}$ $f_{in} = 5.5 \text{ GHz}$ Peak-to-Peak Data Dependent Jitter (Note 14) $f_{DATA} = 3.125 \text{ Gb/s}$ $f_{DATA} = 5 \text{ Gb/s}$ $f_{DATA} = 6.125 \text{ Gb/s}$ | | 0.2 0.2 6 15 15 | 0.5 0.5 15 25 25 | | 0.2 0.2 6 15 15 | 0.5 0.5 15 25 25 | | 0.2 0.2 6 15 15 | 0.5 0.5 15 25 25 | ps |
| V _{INPP} | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 12 and Figures 3, 4, 5, and 6) | 75 | 400 | 2500 | 75 | 400 | 2500 | 75 | 400 | 2500 | mV |
| t _r t _f | Cutput Rise/Fall Times @ 1 G Iz | | 5⊍ | 75 | | 50 | 75 | | £ L | 75 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

^{10.} Measured by forcing $V_{INPP}(MIN)$ from a 50% duty cycle clock source. All loading with an external $R_L = 50~\Omega$ to V_{CC} . Input edge rates 40 ps (20% - 80%).

^{11.} Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw- and Tpw+ @ 1 GHz. 12.V_{INPP}(MAX) cannot exceed V_{CC} - V_{EE}. Input voltage swing is a single-ended measurement operating in differential mode.

^{13.} Additive RMS jitter with 50% duty cycle clock signal.

^{14.} Additive peak-to-peak data dependent jitter with input NRZ data at PRBS 2²³-1.

^{15.} Device-to-device skew is measured between outputs under identical transition and conditions @ 1 GHz.

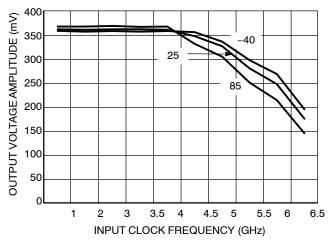


Figure 3. Output Voltage Amplitude vs. Input Clock Frequency and Temperature (V_{inpp} = 400 mV; V_{CC} = 3.3 V)

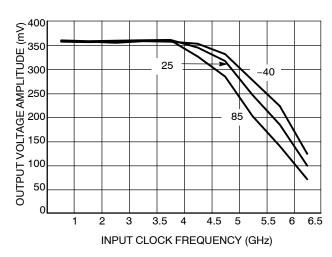


Figure 4. Output Voltage Amplitude vs. Input Clock Frequency and Temperature (V_{inpp} = 75 mV; V_{CC} = 3.3 V)

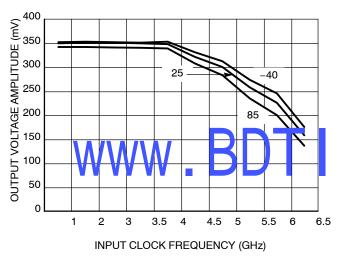


Figure 5. Output Voltage Amplitude vs. Input Clock Frequency and Temperature (V_{inpp} = 400 mV; V_{CC} = 2.5 V)

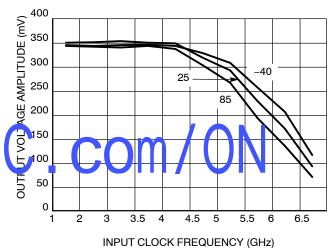


Figure 6. Output Voltage Amplitude vs. Input Clock Frequency and Temperature (V_{inpp} = 75 mV; V_{CC} = 2.5 V)

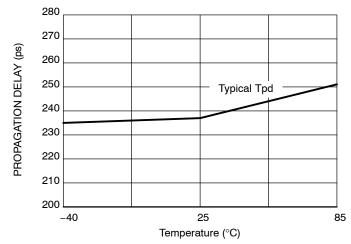


Figure 7. Propagation Delay versus Temperature

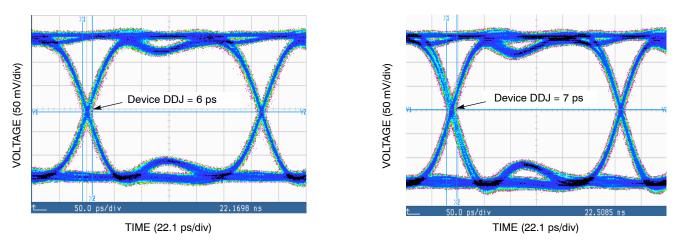


Figure 8. Typical Output Waveform at 3.125 Gb/s with PRBS 2^{23} -1 (V_{inpp} = 75 mV-left and 400 mV-right)

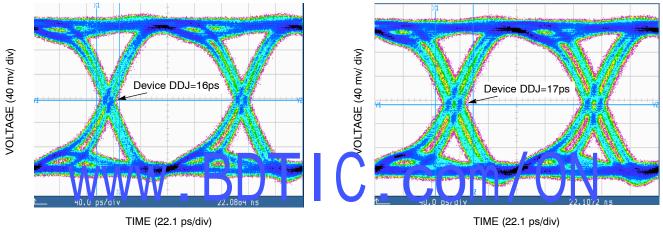


Figure 9. Typical Output Waveform at 5 Gb/s with PRBS 2^{23} -1 (V_{inpp} =75 mV-left and 400 mV-right)

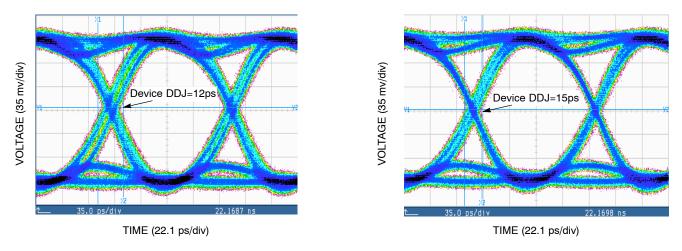


Figure 10. Typical Output Waveform at 6.125 Gb/s with PRBS 2^{23} –1 (V_{inpp} = 75 mV–left and 400 mV–right)

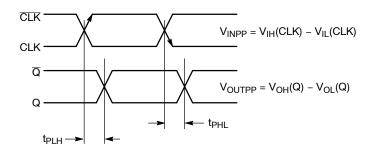


Figure 11. AC Reference Measurement

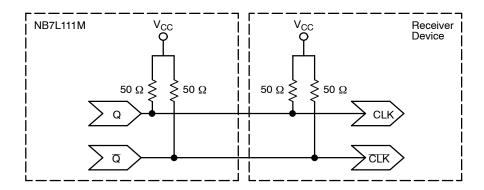


Figure 12. Typical Termination for 16 mA Output Drive and Device Evaluation

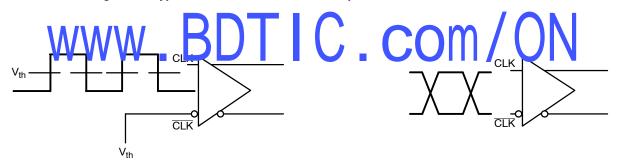


Figure 13. Differential Input Driven Single-Ended

Figure 14. Differential Inputs Driven Differentially

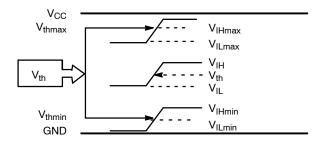


Figure 15. V_{th} Diagram

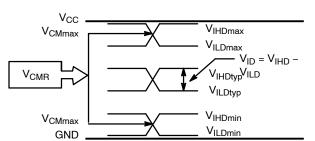


Figure 16. V_{CMR} Diagram

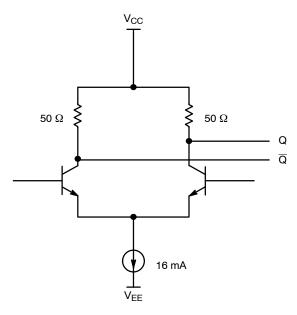


Figure 17. CML Output Structure

Table 7. Interfacing Options

| INTERFACING OPTIONS | CONNECTIONS | | |
|---------------------|--|--|--|
| CML | Connect VTCLK0, VTCLK1, VTCLK1, VTSEL, VTSEL to V _{CC} | | |
| LVDS AC-CCU(LEI) | Connect VTCLK0, VTCLK0 together for CLK0 input; Connect VTCLK1, VTCLK1 together for CLK1 input; Connect VTCLK1, VTCLK1 together for CLK1 input; Connect VTCLK VTCLK together for SEL control input. Lies VTCLK VTCLK TC K0, VTS EL, VT SEL and VTCLK1, /TCLY 1 in u s vithin (/CNR) C in mor Mode Fringe. | | |
| RSECL, LVPECL | Standard ECL termination techniques. See AND8020. | | |
| LVTTL, LVCMOS | An external voltage should be applied to the unused complementary differential input. Nominal voltage 1.5 V for LVTTL and $V_{\rm CC}/2$ for LVCMOS inputs. | | |

Application Information

All NB7L111M inputs can accept LVPECL, CML, LVTTL, LVCMOS and LVDS signal levels. The limitations for differential input signal (LVDS, PECL, or CML) are minimum input swing of 75 mV $_{PP}$ and the maximum input

swing of 2500 mV_{PP}. Within these differential conditions, the input HIGH voltage can range from V_{CC} to 1.2 V. Examples of interfaces are illustrated below in a 50 Ω environment (Z = 50 Ω).

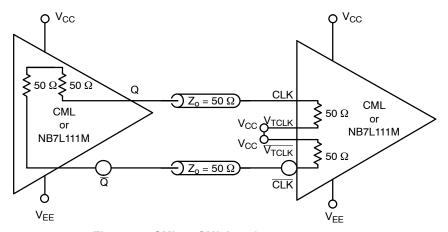
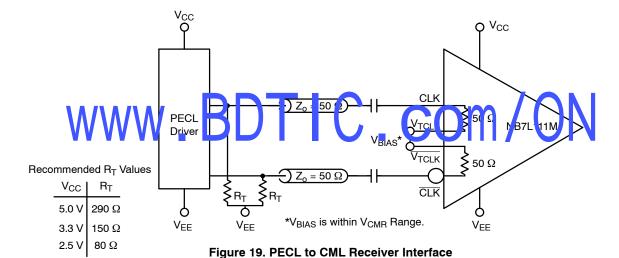
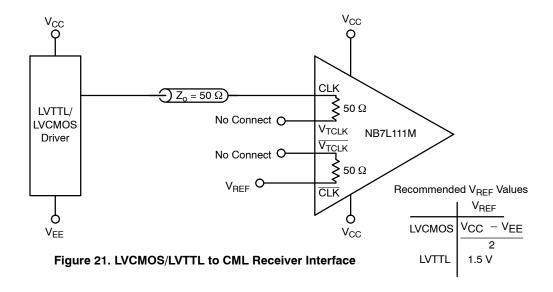


Figure 18. CML to CML Interface



 $\begin{array}{c} V_{CC} \\ \hline \\ LVDS \\ Driver \\ \hline \\ V_{EE} \\ \end{array}$

Figure 20. LVDS to CML Receiver Interface

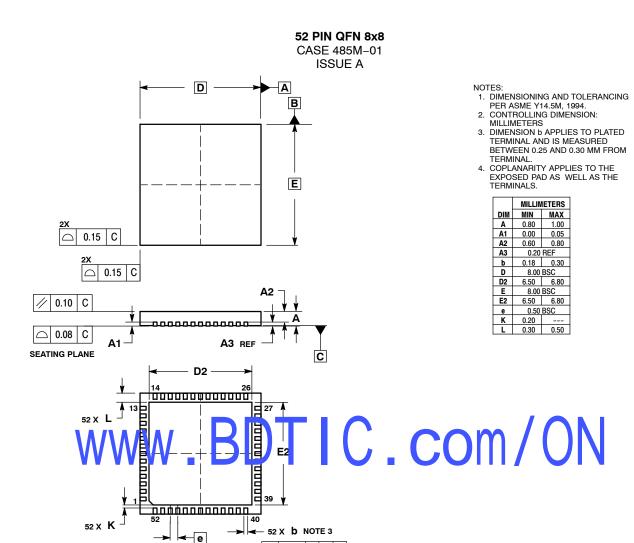


ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|---------------------|-----------------------|
| NB7L111MMN | QFN-52 | 260 Units / Tray |
| NB7L111MMNG | QFN-52 (Pb-Free) | 260 Units / Tray |
| NB7L111MMNR2 | QFN-52 | 2000 / Tape & Reel |
| NB7L111MMNR2G | QFN-52 | 2000 / Tape & Reel |

[†]For information of a 29 and end specific attings, including participant attion and tape sizes please in fer to our lape and Ruel Packaging Specification; Brock unit BRD 8011/D.

PACKAGE DIMENSIONS



0.10 C A 0.05 C

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